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Sam Chou	EMERGING DISPLAY	ISSUE : JAN.29, 2024
OVED BY:	TECHNOLOGIES CORPORATION	TOTAL PAGE: 21
Elvis Wu		VERSION: 4
CUSTOMER	ACCEPTANCE SPEC	CIFICATIONS
FOR	DEL NO.: ET101025HDXA (RoHS) MESSRS:	sailon only.
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DATE:		
BY:		

https://www.edtc.com/ https://smartembeddeddisplay.com/

MODEL NO. VERSION **PAGE** EMERGING DISPLAY TECHNOLOGIES CORPORATION ET101025HDXA 4 0 - 1DOC . FIRST ISSUE AUG.09, 2023 RECORDS OF REVISION REVISED DATE **PAGE** SUMMARY NO. SEP.14, 2023 1 1.1 DATA SHEET FOR CONTROLLER/DRIVER PLEASE REFER TO: SITRONIX ST5821DG SITRONIX ST5084DC→FITIPOWER EK79202B 2. MECHANICAL SPECIFICATIONS (3) MODULE SIZE:232.4W * 157.3H *17D (MAX.) mm→ 232.4W * 157.3H *17.2D (MAX.) mm (4)VIEWING AREA:218.96W * 137.6H mm→217.96W * 136.6H mm 5. TIMING CHARACTERISTICS 4 5.1 LVDS SIGNAL TIMING CHARACTERISTICS→ 5.1 LVDS INPUT TIMING TABLE (DE MODE) 5 6.1 OPTICAL CHARACTERISTICS SYMBOL MIN. TYP. MAX. T_R(rise) +T_F(fall) RESPONSE TIME 25 (0.33) (0.38) WHITE (0.35)(0.30)(0.40)COLOR Rx (0.56) (0,61) (0,66) RED Ry (0.30) (0.35) (0.40) CHROMATICITY (0.32)(0.37) (0.42) GREEN (CENTER) Bx (0.13) (0.18) (0.23) BLUE Ву SYMBOL T_R(rise) +T_F(fall) RESPONSE TIME 25 50 (0.35) (0.40) WHITE (0.33)(0.38) (0.43) (0.65) (0.70) Ry (0.33)(0.38) (0.43) CHROMATICITY (0.29)(0.34) (0.39) GREEN (CENTER) (0.58) (0.63)(0.15) BLUE 7 7. OUTLINE DIMENSIONS MAKR∆: MODIFY V.A. & THICKNESS DIMENSION & TFT PCB->FPC & ADD INSULATED TAPE 8 8. BLOCK DIAGRAM 13.NC→13.CEC 10 10.1 CN1 PIN NO.:13, SYMBOL:NC→CEC, FUNCTION: NON CONNECTION→ CONSUMER ELECTRONICS CONTROL 10.2 CN2 (POWER&LED BACKLIGHT) ADD NOTE (1): TEMP1, TEMP2 12.2.4 INSPECTION METHOD 12 MINOR DEFECT: AQL 1.0→MINOR DEFECT: AQL 1.5 12.3.1 VISUAL DEFECTS CLASSIFICATION 13 TYPE OF DEFECT:MINOR DEFECT, AQL: $1.0 \rightarrow 1.5$ 14, 15 12.3.2 MODULE DEFECTS CLASSIFICATION REVISING THE ENTIRE PAGE OCT.18, 2023 2. MECHANICAL SPECIFICATIONS 1 (8)LCD TYPE:TFT, IPS, TRANSMISSIVE, NORMALLY BLACK→ TFT, IPS, TRANSMISSIVE, NORMALLY BLACK, **ANTI-GLARE** 7 7. OUTLINE DIMENSIONS MAKR .: REMOVE BACKSIDE DRAWING PULL TAPE 8. BLOCK DIAGRAM 8 13.CEC→NC 10 10.1 CN1(HDMI)

PIN NO.:13, SYMBOL:CEC→NC, FUNCTION:CONSUMER

ELECTRONICS CONTROL→NON CONNECTION

MODEL NO. VERSION **PAGE** EMERGING DISPLAY TECHNOLOGIES CORPORATION ET101025HDXA 4 0-2DOC . FIRST ISSUE AUG.09, 2023 REVISION RECORDS OF REVISED DATE **PAGE** SUMMARY NO. JAN.29, 2024 1 2. MECHANICAL SPECIFICATIONS (13)WEIGHT:TBD→327g 3 4. ELECTRICAL CHARACTERISTICS ITEM POWER SUPPLY CURRENT UNIT MAX TBD ITEM TYP. MAX UNIT POWER SUPPLY CURRENT 1.05 1.35 A 6.1 OPTICAL CHARACTERISTICS 5 ITEM CONTRAST RATIO SYMBOL MIN. TYP. MAX. (600)(800)(CENTER) Wx (0.30)(0.35)(0.40)WHITE (0.33) (0.38) (0.43) Rx (0.60)(0.65) (0.70) COLOR RED Ry (0.33)(0.38)(0.43) CHROMATICITY (0.29)(0.34) (0.39) Gx (CENTER) GREEN (0.53) (0.58) (0.63) Gv (0.15) (0.20) (0.25)Bx BLUE (0.17)Ву THE BRIGHTNESS OF В (1500)(1600)MODULE(CENTER) THE UNIFORMITY OF (70)MODULE ITEM SYMBOL MIN. TYP. MAX. CONTRAST RATIO CR 600 800 (CENTER) Wx 0.26 0.31 0.36 WHITE Wy 0.30 0.35 0.40 Rx 0.55 0.60 0.65 COLOR CHROMATICITY RED 0.30 0.40 Ry Gx 0.26 0.31 0.36 (CENTER) GREEN 0.52 0.57 0.62 Bx 0.10 0.15 0.20 BLUE Ву 0.11 0.16 0.21 THE BRIGHTNESS OF 1500 1600 MODULE(CENTER) THE UNIFORMITY OF MODULE 7 7. OUTLINE DIMENSIONS MARK∆: MODIFY BM TAPE OUTLINE & ADD BM TAPE 14 12.3.2 MODULE DEFECTS CLASSIFICATION NO.3, ITEM: DOT DEFECT, ACCEPTABLE COUNT BRIGHT DOT RANDOM N=0 TOTAL BRIGHT AND DARK DOT ACCEPTABLE COUNT BRIGHT DOT RANDOM N≤1 TOTAL BRIGHT AND DARK DOT

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1. GENERAL SPECIFICATIONS

1.1 DATA SHEET FOR CONTROLLER/DRIVER PLEASE REFER TO:

FITIPOWER EK79202B

1.2 MATERIAL SAFETY DESCRIPTION
ASSEMBLIES SHALL COMPLY WITH EUROPEAN ROHS REQUIREMENTS,
INCLUDING PROHIBITED MATERIALS/COMPONENTS CONTAINING LEAD,
MERCURY, CADMIUM, HEXAVALENT CHROMIUM, POLYBROMINATED
BIPHENYLS (PBB) AND POLYBROMINATED
DIPHENYL ETHERS (PBDE), BIS(2-ETHYLHEXYL) PHTHALATE (DEHP), BUTYL
BENZYL PHTHALATE (BBP), DIBUTYL PHTHALATE (DBP), DIISOBUTYL
PHTHALATE (DIBP).

2. MECHANICAL SPECIFICATIONS

(1) DISPLAY SIZE	10.1 inch
(2) NUMBER OF DOTS	1280(RGB)W * 800H DOTS
(3) MODULE SIZE	232.4W * 157.3H *17.2D (MAX.) mm
(4) VIEWING AREA	217.96W * 136.6H mm
(5) ACTIVE AREA	216.96W * 135.6H mm
(6) DOT SIZE	0.0565W * 0.1695H mm
(7) PIXEL SIZE	0.1695W * 0.1695H mm
(8) LCD TYPE	TFT, IPS, TRANSMISSIVE,
A	NORMALLY BLACK, ANTI-GLARE
(9) COLOR	16.7M
(10) VIEWING DIRECTION	SUPER WIDE VIEW
(11) BACK LIGHT	LED , COLOR : WHITE
(12) INTERFACE MODE	HDMI 1.4
(13) WEIGHT	327g

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3. ABSOLUTE MAXIMUM RATINGS

3.1 ELECTRICAL ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	MIN.	MAX.	UNIT	REMARK
POWER SUPPLY VOLTAGE	VDD-VSS		12.5	V	
STATIC ELECTRICITY				V	NOTE (1)

NOTE (1): LCM SHOULD BE GROUND DURING LCM HANDLING.

NOTE (2): THE ABSOLUTE MAXIMUM RATING VALUES OF THIS PRODUCT ARE NOT ALLOWED TO BE EXCEEDED AT ANY TIMES. SHOULD A MODULE BE USED WITH ANY OF THE ABSOLUTE MAXIMUM RATINGS EXCEEDED, THE CHARACTERISTICS OF THE MODULE MAY NOT BE RECOVERED, OR IN AN EXTREME CASE, THE MODULE MAY BE PERMANENTLY DESTROYED.

3.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS

ITEM	OPERATING		STORAGE		REMARK	
I I EMI	MIN.	MAX.	MIN.	MAX.	KEWAKK	
AMBIENT TEMPERATURE	-30 °C	85 °C	-40 °C	85 °C	NOTE (1),(2),(3),(4)	
HUMIDITY	NOTI	E(3)	NOTI	E(3)	WITHOUT CONDENSATION	
VIBRATION		2.45 m/s ² (0.25 G)	1000	11.76 m/s ² (1.2 G)	10~100 Hz XYZ DIRECTIONS 1 HR EACH	
SHOCK	T)	29.4 m/s ² (3 G)		490.0 m/s ² (50 G)	10ms XYZ DIRECTIONS 1 TIME EACH	

- NOTE (1): THE ABSOLUTE MAXIMUM RATINGS OF THIS PRODUCT SHOULD NOT BE EXCEEDED AT ANY TIME. IF THESE RATINGS ARE EXCEEDED, THE PRODUCT'S PERFORMANCE IS NOT GUARANTEED AND THE PRODUCT MAY EXPERIENCE PERMANENT DAMAGE.
- NOTE (2): BACKGROUND COLOR CHANGES SLIGHTLY DEPENDING ON AMBIENT TEMPERATURE THIS PHENOMENON IS REVERSIBLE.
- NOTE (3): Ta ≤ 60°C: 90%RH MAX. (96HRS MAX.)

 Ta > 60°C: ABSOLUTE HUMIDITY MUST BE LOWER THAN THE HUMIDITY OF 90%RH

 AT 60°C. (96HRS MAX.)
- NOTE (4): WHEN THE LCD MODULE IS OPERATED AT A HIGHER AMBIENT TEMPERATURE THAN 60°C, THE PWM DUTY CYCLE OF THE LED BACKLIGHT SHOULD BE ADJUSTED TO BE LESS THAN (TBD)%. IF THE MODULE IS OPERATED AT A HIGHER DUTY CYCLE THAN (TBD)%, THEN THERE IS A POSSIBILITY OF DISTORTION AND IRREGULARITY OF THE PICTURE DUE TO LIQUID CRYSTAL BEHAVIOR.

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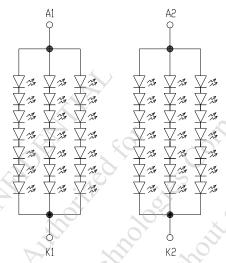
4. ELECTRICAL CHARACTERISTICS

 $Ta = 25 \, ^{\circ}C$

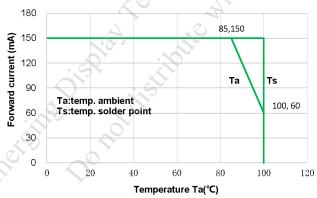
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REMARK
POWER SUPPLY VOLTAGE	VDD-VSS	_	11.5	12.0	12.5	V	
POWER SUPPLY CURRENT	IDD	VDD-VSS =12.0V		1.05	1.35	A	NOTE (1)
LOGIC HIGH INPUT VOLTAGE FOR BL_EN, BL_PWM	VIH	_	1.6		_	V	
LOGIC LOW INPUT VOLTAGE FOR BL_EN, BL_PWM	VIL	_	_	_	0.8	V	
LED LIFE TIME	_	IF=70 mA (PER LED)	50000	_	_	HRS	NOTE (4) NOTE (5)

NOTE (1): THE DISPLAY PATTERN IS ALL "WHITE".

NOTE (2): INTERNAL CIRCUIT DIAGRAM OF BACKLIGHT.



NOTE (3): AMBIENT TEMP. VS. ALLOWABLE FORWARD CURRENT.(PER LED)



NOTE (4): CONDITIONS; Ta=25 °C, CONTINUOUS LIGHTING

NOTE (5): DEFINITIONS OF LIFE TIME:

LCM LUMINANCE BECOMES HALF OF THE INITIAL VALUE.

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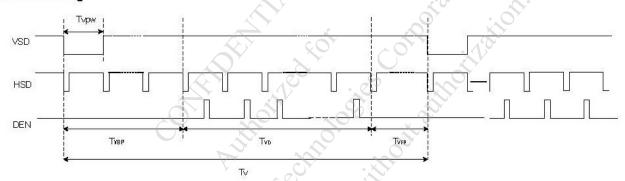
5. TIMING CHARACTERISTICS

5.1 LVDS INPUT TIMING TABLE (DE MODE)

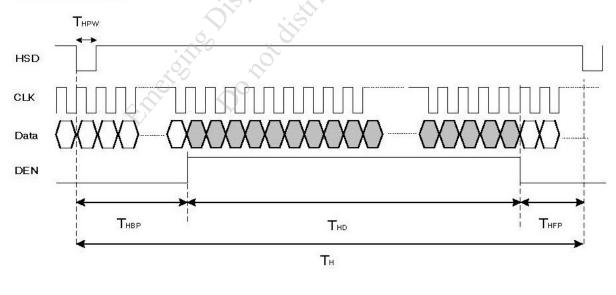
ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
DCLK FREQUENCY @FRAME RATE=60Hz (LVDS)	Fdclk	68.2	72.4	78.5	MHz
HORIZONTAL DISPLAY AREA	Тнр		1280		DCLK
HSYNC PERIOD TIME	Тн	1380	1440	1500	DCLK
HSYNC BLANKING	THBP+THFP	100	160	220	DCLK
VERTICAL DISPLAY AREA	Tvd		800		Н
VSYNC PERIOD TIME	Tv	824	838	872	Н
VSYNC BLANKING	T _{VBP} +T _{VFP}	24	38	72	Н

NOTE: TIMING SETTING BASE ON 60Hz, FREQUENCY CAN BE ADJUSTED ACCORDING TO NEEDS, AS LONG AS IT DOES NOT AFFECT THE DISPLAY.

Vertical timing



Horizontal timing



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6. OPTICAL CHARACTERISTICS

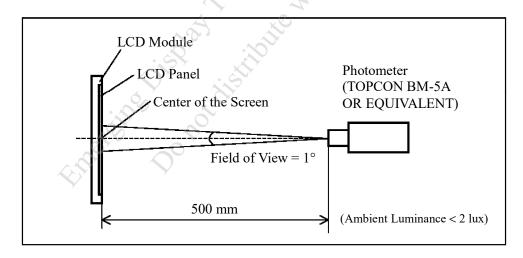
6.1 OPTICAL CHARACTERISTICS

Ta=25±2°C

t		1							1a 23±2 C
ITEM SYN		SYMBOL	CONDITION		MIN.	TYP.	MAX.	UNIT	REMARK
		θ y+		θx=0°	75	85	_	deg	
VIEWING ANGLE		θу-	CD>10	0 X–0	75	85	_	deg	NOTE (2)
VIEWING ANGLE		$\theta x+$	CK210	CR≥10	75	85		deg	NOTE (3)
		θx-		θy=0°	75	85		deg	
CONTRAST RATIO (CENTER)		CR			600	800		_	NOTE (3)
RESPONSE TIME		T _R (rise) +T _F (fall)	$\theta x=0^{\circ}, \theta y=0^{\circ}$		_	25	50	msec	NOTE (4)
	WHITE	Wx			0.26	0.31	0.36		
	WHITE	Wy			0.30	0.35	0.40		
COLOD	RED	Rx	4 .	4	0.55	0.60	0.65		
COLOR	KED	Ry			0.30	0.35	0.40		NOTE (5)
CHROMATICITY (CENTER)	CDEEN	Gx	$\theta x=0^{\circ},$	$\theta y=0^{\circ}$	0.26	0.31	0.36	· ·	NOTE (5)
(CENTER)	GREEN	Gy A	VDD-V	SS=12V	0.52	0.57	0.62	Y —	
	DITE	Bx		/L=ON	0.10	0.15	0.20		
	BLUE	By	PWM=	=100%	0.11	0.16	0.21		
THE BRIGHTNESS OF MODULE(CENTER)		В	180	y ´	1500	1600		cd/m ²	NOTE (6)
THE UNIFORMITY OF MODULE		<u></u>	OTT	2002	70			%	NOTE (7)

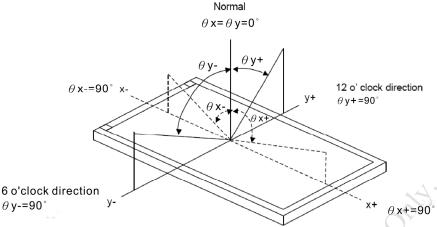
NOTE (1): TEST CONDITION:

AFTER STABILIZING AND LEAVING THE PANEL ALONE AT A GIVEN TEMPERATURE FOR 30 MINUTES. MEASUREMENT SHOULD BE EXECUTED IN A STABLE, WINDLESS, AND DARK ROOM.



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NOTE (2): DEFINITION OF VIEWING ANGLE:

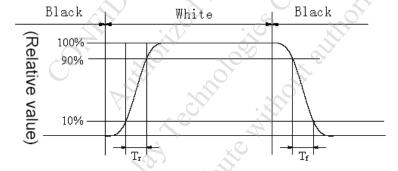


NOTE (3): DEFINITION OF CONTRAST RATIO (CR):

MEASURED AT THE CENTER POINT OF MODULE

 $\label{eq:contrast} \text{CONTRAST} \quad \text{RATIO(CR)} = \frac{\text{BRIGHTNESS MEASURED WHEN LCD IS AT "WHITE STATE"}}{\text{BRIGHTNESS MEASURED WHEN LCD IS AT "BLACK STATE"}}$

NOTE (4): DEFINITION OF RESPONSE TIME: TR AND TF
THE FIGURE BELOW IS THE OUTPUT SIGNAL OF THE PHOTO DETECTOR.



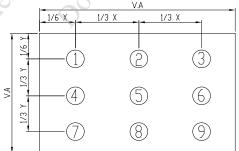
NOTE (5): DEFINITION OF COLOR CHROMATICITY

(a)100% RGB PIXEL DATA TRANSMISSION WHEN ALL THE INPUT TERMINALS OF MODULE ARE ELECTRICALLY POWERED ON.

(b)MEASURED AT THE CENTER POINT OF MODULE

NOTE (6): MEASURED THE BRIGHTNESS OF WHITE STATE AT CENTER POINT.

NOTE (7): (a) DEFINITION OF BRIGHTNESS UNIFORMITY



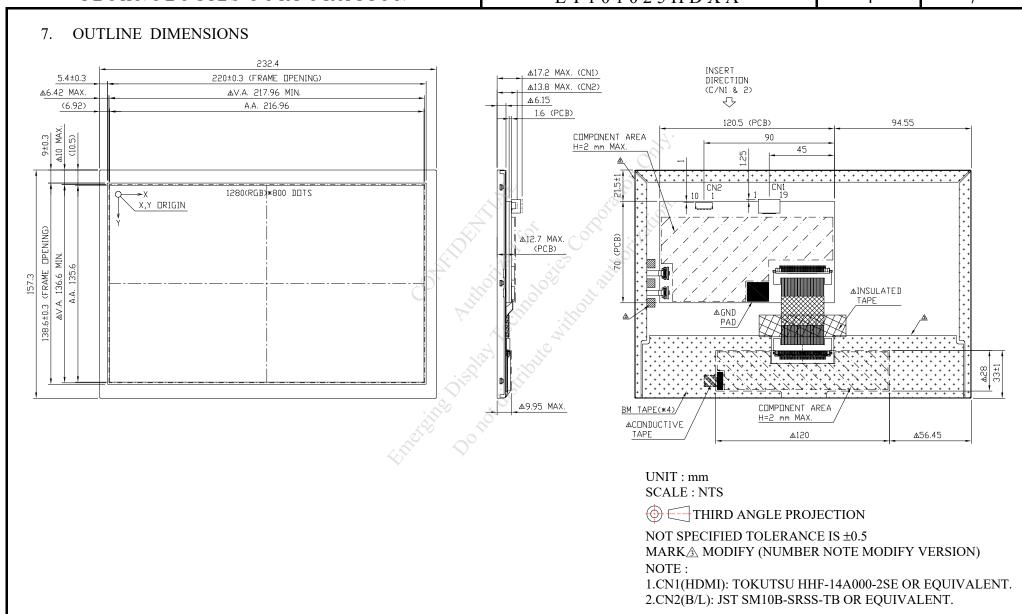
」UNIT:mm

(b)THE BRIGHTNESS UNIFORMITY CALCULATING METHOD

UNIFORMITY: MINIMUM BRIGHTNESS

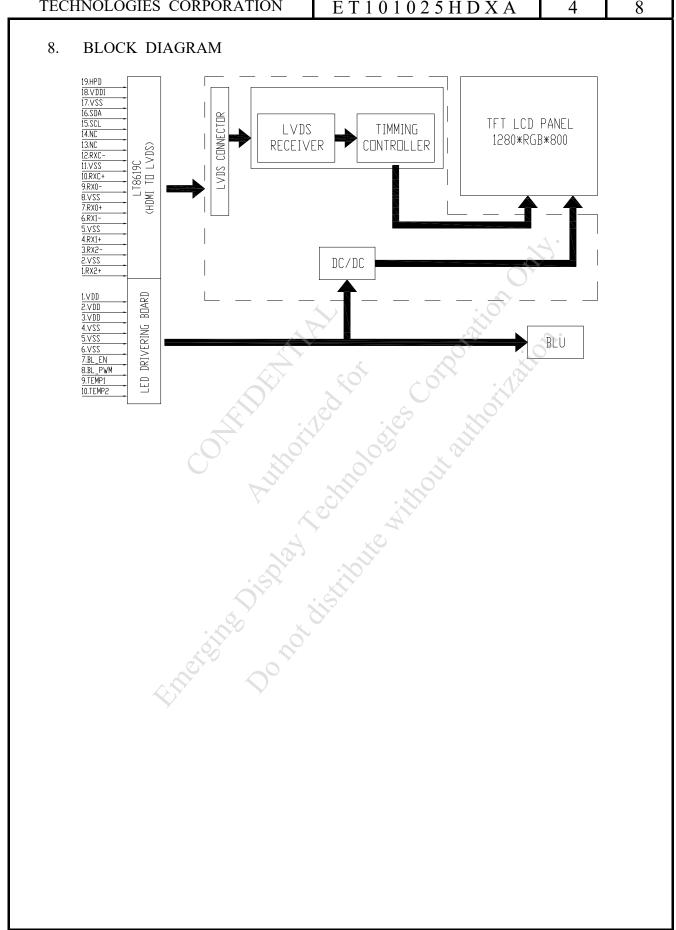
*100%

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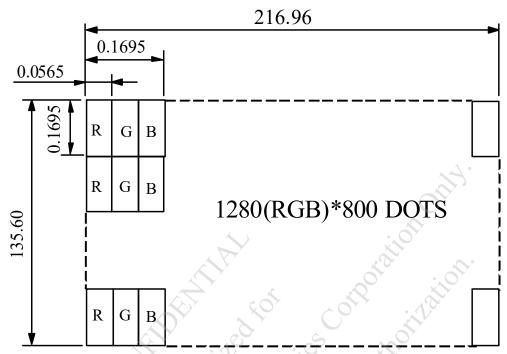


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UNIT : mm SCALE : NTS

NOT SPECIFIED TOLERANCE IS ± 0.1 DOTS MATRIX TOLERANCE IS ± 0.01

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10. INTERFACE SIGNALS

10.1 CN1(HDMI)

PIN NO.	SYMBOL	FUNCTION
1	RX2+	TMDS CHANNEL 2 DATA+
2	VSS	GROUND
3	RX2-	TMDS CHANNEL 2 DATA-
4	RX1+	TMDS CHANNEL 1 DATA+
5	VSS	GROUND
6	RX1-	TMDS CHANNEL 1 DATA-
7	RX0+	TMDS CHANNEL 0 DATA+
8	VSS	GROUND
9	RX0-	TMDS CHANNEL 0 DATA-
10	RXC+	TMDS CLOCK+
11	VSS	GROUND
12	RXC-	TMDS CLOCK-
13	NC	NON CONNECTION
14	NC	NON CONNECTION
15	SCL	DDC CLOCK
16	SDA	DDC DATA
17	VSS	GROUND
18	VDD1	POWER SUPPLY VOLTAGE FOR HDMI (+5V)
19	HPD	HOT PLUG DETECT

10.2 CN2 (POWER&LED BACKLIGHT)

PIN NO.	SYMBOL	FUNCTION
1	VDD	POWER SUPPLY VOLTAGE (+12V)
2	VDD	POWER SUPPLY VOLTAGE (+12V)
3	VDD	POWER SUPPLY VOLTAGE (+12V)
4	VSS	GROUND
5	VSS	GROUND
6	VSS	GROUND
7	BL_EN	BACKLIGHT LED ON/OFF CONTROL
8	BL_PWM	BACKLIGHT LED BRIGHTNESS CONTROL
9	TEMP1	TEMPERATURE SENSOR PIN1
10	TEMP2	TEMPERATURE SENSOR PIN2

NOTE (1): TEMP1, TEMP2

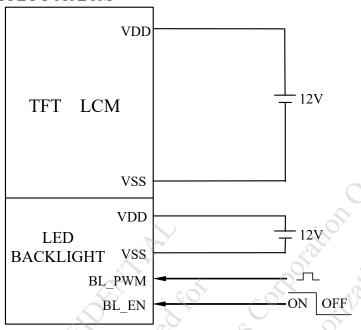
THERMISTOR CHARACTERISTICS(EDT MATERIAL: TH20-3H103FT)

ITEM	SPECIFICATION	CONDITION
RESISTANCE	10K OHM ±1%	ZERO-POWER RESISTANCE AT 25°C
B-CONSTANT	3370K ±1%	B-VALUE BETWEEN 25 TO 50°C
MAXIMUM POWER DISSIPATION	500mW	AT 25°C
HEAT DISSIPATION	5.0mW/°C	
OPERATING TEMPERATURE RANGE	-40°C~125°C	
RoHS	COMPLIANT	

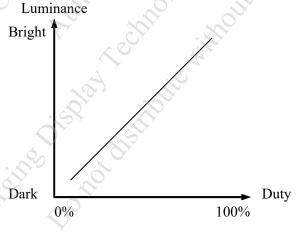
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11. POWER SUPPLY

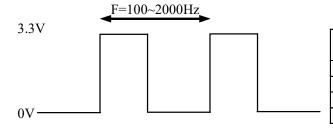
11.1 POWER SUPPLY FOR LCM



NOTE (1) : ADJUST THE PWM SIGNAL IN ORDER TO CONTROL LED BACKLIGHT'S BRIGHTNESS. THE HIGHER THE DUTY CYCLE, THE HIGHER THE BRIGHTNESS



NOTE (2): PWM SIGNAL OPERATION FREQUENCY IS 100~2000Hz AND DIMMING DUTY.



PWM Dimming	Dimming Duty	
Frequency[Hz]	Min[%]	Max[%]
$100 < F_{DIM} < 200$	0.1	100
$200 < F_{DIM} < 500$	0.4	100
$200 < F_{DIM} < 1K$	0.8	100
$1K < F_{DIM} < 2K$	1.5	100

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12. INSPECTION CRITERIA

12.1 APPLICATION

THIS INSPECTION STANDARD IS TO BE APPLIED TO THE LCD MODULE DELIVERED FROM EMERGING DISPLAY TECHNOLOGIES CORP.(E.D.T) TO CUSTOMERS

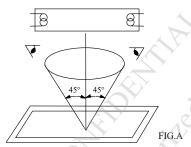
12.2 INSPECTION CONDITIONS

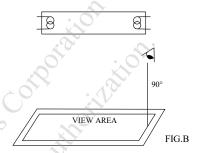
12.2.1 (1)OBSERVATION DISTANCE: 45±5cm

(2) VIEWING ANGLE: ±45°

±45° (FOR SECTION WITHIN VIEWING AREA), REFER TO FIG.A 90° (FOR SECTION OUTSIDE OF VIEWING AREA), REF TO FIG.B PERPENDICULAR TO MODULE SURFACE

VIEWING ANGLE SHOULD BE SMALLER THAN 45°





THE INSPECTION CRITERIA IS ACCORDING TO LINE OF SIGHT. INSPECTION SHALL BE MADE WITHIN THE HALF SECTION OF THE VIEWING CONE GENERATED BY LINE SEGMENT OF 45° WITH RESPECT TO THE VERTICAL AXIS FROM CENTER VERTEX OF LCD, THE FLUORESCENT LAMP AND THE CONE AXIS MUST BE PERPENDICULAR TO THE LCD SURFACE.

IF THE DEFECTS ARE OUTSIDE OF VIEWING AREA, IT SHALL BE INSPECTED BY 90° WITH RESPECT TO THE VERTICAL AXIS FROM EDGE OF VIEWING AREA.

12.2.2 ENVIRONMENT CONDITIONS:

AMBIEN	25±5°C	
AMB	$65 \pm 20\%$ RH	
AMBIENT COSMETIC INSPECTION		600~800 lux
ILLUMINATION FUNCTIONAL INSPECTION		300~500 lux
INS	PECTION TIME	15 secs

12.2.3 INSPECTION LOT QUANTITY PER DELIVERY LOT FOR EACH MODEL

12.2.4 INSPECTION METHOD

A SAMPLING INSPECTION SHALL BE MADE ACCORDING TO THE FOLLOWING PROVISIONS TO JUDGE THE ACCEPTABILITY (a)APPLICABLE STANDARD:

ANSI/ ASQ Z1.4 NORMAL INSPECTION LEVEL II

(b)AQL: MAJOR DEFECT: AQL 0.65 MINOR DEFECT: AQL 1.5

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12.3 INSPECTION STANDARDS

12.3.1 VISUAL DEFECTS CLASSIFICATION

TYPE OF DEFECT	INSPECTION ITEM	DEFECT FEATURE	AQL
	1.DISPLAY ON	DEFECT TO MISS SPECIFIED DISPLAY FUNCTION, FOR ALL AND SPECIFIED DOTS EX: DISCONNECTION, SHORT CIRCUIT ETC	
MAJOR DEFECT	2.BACKLIGHT	NO LIGHT FLICKERING AND OTHER ABNORMAL ILLUMINATION	0.65
	3.DIMENSIONS	• SUBJECT TO INDIVIDUAL ACCEPTANCE SPECIFICATIONS	
MINOR DEFECT	1.DISPLAY ZONE 2.BEZEL ZONE	 BLACK/WHITE SPOT BUBBLES ON POLARIZER NEWTON RING BLACK/WHITE LINE SCRATCH CONTAMINATION UNEVEN COLOR SPREAD STAINS SCRATCHES FOREIGN MATTER 	1.5
	3.SOLDERING 4.DISPLAY ON (ALL ON)	 INSUFFICIENT SOLDER SOLDERED IN INCORRECT POSITION CONVEX SOLDERING SPOT SOLDER BALLS SOLDER SCRAPS LIGHT LINE 	_

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12.3.2 MODULE DEFECTS CLASSIFICATION

NO.	ITEM	CRITERIA				
1	DISPLAY ON INSPECTION	I. INCORRECT PATTERN 2. MISSING SEGMENT 3. DIM SEGMENT 4. OPERATING VOLTAGE BEYOND SPEC				
2	OVERALL DIMENSIONS	1. OVERALL DIMENSION BEYOND SPEC				
3	DOT DEFECT	AND BLUE SCR 2. ITEMS BRIGHT DOT DARK DOT DISTANCE TOTAL BRIGHT AND MICRO BRIGHT DOT SMALL BRIGHT DOT NOTE: 1. THE DEFINIT THE SIZE OF REGARDED THE BRIGHT FILTER 2. BRIGHT DOT DOTS APPEA PANEL IS DI 3. DARK DOT: DOTS APPEA	RANDOM 2 DOTS ADJACENT 3 DOTS ADJACENT 3 DOTS ADJACENT 3 DOTS ADJACENT 3 DOTS ADJACENT MINIMUM DISTAN BRIGHT DOT MINIMUM DISTAN DARK DOTS DARK DOTS TO A DEFECTIVE AS ONE DEFECT TO TO THE SPLAYING UNITAL AR DARK AND ITAL AR DARK	DOT OVER 1/TIVE DOT. MOST BE VISOUNCHANGED UNCHANGED	ACCEPTABLE COUNT N=0 N=0 N=0 N=0 N=0 N=0 L≥15mm N≤5 N=0 (1)N≤4 (2)N≤3 WITHIN 20mm DIAMETER AREA ZOF WHOLE DOT IBLE THROUGH A ED IN SIZE IN WHICH ON SIZE IN WHICH O	IS 5% N
4	FOREIGN BLACK/WHITE/ BRIGHT LINE/ SCRATCH/BUBBLES OF VIEWING AREA	LENGTH: L IGNORE L≤5.0 5.0 < L WIDTH: W mm,	WIDTH: W $W \le 0.07$ $0.07 < W \le 0.1$ $0.1 < W$ LENGTH: L m	PERMISSIBLE IGNORE 5 NONE	NO.	
5	FOREIGN MATTER \ BLACK SPOTS \ WHITE SPOTS \ DENT (INCLUDING LIGHT LEAKAGE DUE TO POLARIZING PLATES PINHOLES, ETC.)	AVERAGE DIAM D \leq 0 0.3 < D 0.5 < NOTE : DIAMET	1.3 ≤ 0.5 D	IC	PIECES PERMITTED GNORE 5 NONE	

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NO.	ITEM	CRITERIA				
			AVERAGE DIAMETER (mm): D	NUMBER OF PIECES PERMITTED		
		DUDDI E ON THE	D ≤ 0.3	IGNORE		
		BUBBLE ON THE POLARIZER	$0.3 < D \le 0.5$	N ≤ 5		
		FOLARIZER	0.5 < D	NONE		
			D ≤ 0.1	IGNORE		
		SURFACE STAINS	$0.1 < D \le 0.5$	N ≤ 6		
			0.5 < D	NONE		
		G CD ATTOLIES	W ≤ 0.05	IGNORE		
		SCRATCHES	$0.05 < W \le 0.1, 2 \le L \le 5$	N≤4		
7	DENT/BUBBLE ON THE POLARIZER LINE DEFECT ON	NOTE: (1)POLARIZER BUBBLE IS DEFINED AS THE BUBBLE APPEARS ON ACTIVE DISPLAY AREA. THE DEFECT OF POLARIZER BUBBLE SHALL BE IGNORED IF THE POLARIZER BUBBLE APPEARS ON THE OUTSIDE OF ACTIVE DISPLAY AREA. (2)THE EXTRANEOUS SUBSTANCE IS DEFINED AS IT CAN BE OBSERVED WHEN THE MODULE IS POWER ON. (3)THE DEFINITION OF AVERAGE DIAMETER, D IS DEFINED AS FOLLOWING. AVERAGE DIAMETER (D)=(a+b)/2				
	DISPLAY	OBVIOUS VERTICAL OR HORIZONTAL LINE DEFECT IS NOT ALLOWED MURA NOT VISIBLE THROUGH 5% ND FILTER				
8	MURA ON DISPLAY	MURA NOT VISIBLE THROUGH 5% ND FILTER				
9	UNEVEN COLOR SPREAD, COLORATION	1. TO BE DETERMINED BASED UPON THE STANDARD SAMPLE.				
10	BEZEL APPEARANCE	BEZEL MAY NOT HAVE RUST, BE DEFORMED OR HAVE FINGER PRINTS STAINS OF OTHER CONTAMINATION. BEZEL MUST COMPLY WITH JOB SPECIFICATIONS.				
11	PCB	 THERE MAY NOT BE MORE THAN 2mm OF SEALANT OUTSIDE THE SEAL AREA ON THE PCB, AND THERE SHOULD BE NO MORE THAN THREE PLACES. NO OXIDATION OR CONTAMINATION PCB TERMINALS. PARTS ON PCB MUST BE THE SAME AS ON THE PRODUCTION CHARACTERISTIC CHART. THERE SHOULD BE NO WRONG PARTS, MISSING PARTS OR EXCESS PARTS. THE JUMPER ON THE PCB SHOULD CONFORM TO THE PRODUCT CHARACTERISTIC CHART. IF SOLDER GETS ON BEZEL TAB PADS, LED PAD, ZEBRA PAD OR SCREW HOLD PAD; MAKE SURE IT IS SMOOTHED DOWN. 				

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1. NO SOLDERING FOUND ON THE SPECIFIED PLACE	
2. INSUFFICIENT SOLDER (a)LSI, IC A POOR WETTING OF SOLDER IS BETWEEN LOWE "HEEL" OF LEAD AND PAD SOLDER FILLET (b)CHIP COMPONENT - SOLDER IS LESS THAN 50% OF SIDES AND FRON WETTING SOLDER FILLET 1/2 SOLDER FILLET 1/2 SOLDER FILLET 1/2 3. PARTS ALIGNMENT (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE 2. INSUFFICIENT SOLDER (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE 2. INSUFFICIENT SOLDER (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE 2. INSUFFICIENT SOLDER (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE 2. INSUFFICIENT SOLDER (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE 2. INSUFFICIENT SOLDER (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (b)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (b)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (b)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUT THE SPECIFIED FLACE (c)LSI, IC LEAD WIDTH IS WITH IS	T FACE S THAN 25% OI ED

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NO.	ITEM	CRITERIA
		(b)CHIP COMPONENT COMPONENT IS OFF CENTER, AND MORE THAN 50% OF THE LEADS IS OFF THE PAD OUTLINE
12 SOLDER	ING	
		 4. NO UNMELTED SOLDER PASTE MAY BE PRESENT ON THE PCB. 5. NO COLD SOLDER JOINTS, MISSING SOLDER CONNECTIONS, OXIDATION OR ICICLE. 6. NO RESIDUE OR SOLDER BALLS ON PCB. 7. NO SHORT CIRCUITS IN COMPONENTS ON PCB.
13 BACKLIO	GHT	 NO LIGHT FLICKERING AND OTHER ABNORMAL ILLUMINATION SPOTS OR SCRATCHES THAT APPEAR WHEN LIT MUST BE JUDGED USING LCD SPOT, LINES AND CONTAMINATION STANDARDS. BACKLIGHT DOESN'T LIGHT OR COLOR IS WRONG.
14 GENERA APPEAR.		 NO OXIDATION, CONTAMINATION, CURVES OR, BENDS ON INTERFACE PIN (OLB) OF TCP. NO CRACKS ON INTERFACE PIN (OLB) OF TCP. NO CONTAMINATION, SOLDER RESIDUE OR SOLDER BALLS ON PRODUCT. THE IC ON THE TCP MAY NOT BE DAMAGED, CIRCUITS. THE UPPERMOST EDGE OF THE PROTECTIVE STRIP ON THE INTERFACE PIN MUST BE PRESENT OR LOOK AS IF IT CAUSE THE INTERFACE PIN TO SEVER. THE RESIDUAL ROSIN OR TIN OIL OF SOLDERING (COMPONENT OR CHIP COMPONENT) IS NOT BURNED INTO BROWN OR BLACK COLOR. SEALANT ON TOP OF THE ITO CIRCUIT HAS NOT HARDENED. PIN TYPE MUST MATCH TYPE IN SPECIFICATION SHEET. LCD PIN LOOSE OR MISSING PINS. PRODUCT PACKAGING MUST THE SAME AS SPECIFIED ON PACKAGING SPECIFICATION SHEET. PRODUCT DIMENSION AND STRUCTURE MUST CONFORM TO PRODUCT SPECIFICATION SHEET. THE APPEARANCE OF HEAT SEAL SHOULD NOT ADMIT ANY DIRT AND BREAK.

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THE LCD WITH EXTENSIVE CRACK IS NOT ACCEPTABLE GENERAL GLASS CHIP:	NO.	ITEM		CRITERIA	
Separation Sep			THE LCD WITH EXTENSIVE (CRACK IS NOT ACCEPTABLE	
Separation Sep			GENERAL GLASS CHIP:	a b	c
CORNER PART: SEALANT AREA AND LCD			ь	≤ t/2 < VIEWING AREA	≤ 1/8X
SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS CORNER PART: SU2			a	$t/2 > , \le 2t \qquad \qquad \le W/2 \qquad \qquad :$	≤ 1/8X
SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS CORNER PART: SU2				*W=DISTANCE BETWEEN	
PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS CORNER PART:					
TECT SIDE LENGTH SU2			` `		
CORNER PART: Corner part					
CORNER PART: Section Corner Corn					
CORNER PART: S V2 VIEWING AREA 51/8X S V2 S V V V S V2 S V V S V2 S V V S V S V S V S V S V S V S V S S V W-DISTANCE BETWEEN SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS S S S S S S S S S			1	t = GLASS THICKNESS	
CORNER PART: S V2 VIEWING AREA 51/8X S V2 S V V V S V2 S V V S V2 S V V S V S V S V S V S V S V S V S S V W-DISTANCE BETWEEN SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS S S S S S S S S S			w c		
CORNER PART: S V2 VIEWING AREA 51/8X S V2 S V V V S V2 S V V S V2 S V V S V S V S V S V S V S V S V S S V W-DISTANCE BETWEEN SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS S S S S S S S S S					
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CORNER PART: B			b		
CORNER PART: B					
CORNER PART . $ \frac{\leq v2}{>v2} \frac{< \text{VIEWING AREA}}{\leq w2} \frac{\leq 1/8X}{\leq 1/8X} $ *W=DISTANCE BETWEEN SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS $ \frac{a}{\leq t} \frac{b}{\leq 0.5 \text{mm}} \frac{\leq 1/8X}{\leq 1/8X} $ *X=LCD SIDE WIDTH t = GLASS THICKNESS $ \frac{a}{\leq t} \frac{b}{\leq 0.5 \text{mm}} \frac{c}{\leq 1/8X} \frac{c}{\leq 1/8X} $ *X=LCD SIDE WIDTH t = GLASS THICKNESS $ \frac{a}{\leq t} \frac{b}{\leq t} \frac{c}{\leq t/8X} \frac{c}{\leq t} $ *X=LCD SIDE WIDTH t = GLASS THICKNESS L=ELECTRODE PAD LENGTH 0F GLASS CHIPPING THE ITO TERMINA OVER 2/3 OF THE ITO MUST REMAIN AND BE, INSPECTED ACCORDING TO ELECTRODE TERMINAL SPECIFICATIONS 0F THE PRODUCT WILL BE HEAT SEALED BY THE CUSTOMER, THE ALIGNMENT MARK MUST NOT			a		
CRACKED GLASS SUBSTANCE BETWEEN			CODNED DADT:	a b	С
*W=DISTANCE BETWEEN SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS CHIP ON ELECTRODE PAD *X=LCD SIDE WIDTH t = GLASS THICKNESS *X=LCD SIDE WIDTH t = GLASS THICKNESS *X=LCD SIDE WIDTH t = GLASS THICKNESS L=ELECTRODE PAD LENGTH 0IF GLASS CHIPPING THE ITO TERMINA OVER 2/3 OF THE ITO MUST REMAIN AND BE, INSPECTED ACCORDING TO ELECTRODE TERMINAL SPECIFICATIONS ②IF THE PRODUCT WILL BE HEAT SEALED BY THE CUSTOMER, THE ALIGNMENT MARK MUST NOT			CORNER PART .	≤ t/2 < VIEWING AREA	≤ 1/8X
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SEALANT AREA AND LCD PANEL EDGE X = LCD SIDE LENGTH t = GLASS THICKNESS CHIP ON ELECTRODE PAD				*W=DISTANCE BETWEEN	
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X = LCD SIDE LENGTH t = GLASS THICKNESS CHIP ON ELECTRODE PAD a b c ≤t ≤0.5mm ≤1/8X * X=LCD SIDE WIDTH t = GLASS THICKNESS a b c ≤t ≤1/8X ≤L *X=LCD SIDE WIDTH t = GLASS THICKNESS L=ELECTRODE PAD LENGTH © IF GLASS CHIPPING THE ITO TERMINA OVER 2/3 OF THE ITO MUST REMAIN AND BE, INSPECTED ACCORDING TO ELECTRODE TERMINAL SPECIFICATIONS ② IF THE PRODUCT WILL BE HEAT SEALED BY THE CUSTOMER, THE ALIGNMENT MARK MUST NOT			a		
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CHIP ON ELECTRODE PAD a					
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*X=LCD SIDE WIDTH t =GLASS THICKNESS a			CHIR ON ELECTRODE DAD	a h	C
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				BE DEMAGED	

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13. RELIABILITY TEST

13.1 STANDARD SPECIFICATIONS FOR RELIABILITY OF LCD MODULE

NO.	ITEM	DESCRIPTION
1	HIGH TEMPERATURE TEST(OPERATION)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +85°C FOR 240 HRS
2	LOW TEMPERATURE TEST(OPERATION)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -30°C FOR 240 HRS
3	HIGH TEMPERATURE TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +85°C FOR 240 HRS
4	LOW TEMPERATURE TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -40°C FOR 240 HRS
5	HIGH TEMPERATURE / HUMIDITY TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT 60°C, 90% RH 240 HRS
6	THERMAL SHOCK (NOT OPERATED)	THE SAMPLE SHOULD BE ALLOWED TO STAND THE FOLLOWING 10 CYCLES OF OPERATION: +85°C -40°C 30 min 5 min 30 min 5 min 1 5 min 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
7	ESD (ELECTROSTATIC DISCHARGE) (NOT OPERATED)	AIR DISCHARGE ± 12KV CONTACT DISCHARGE ± 8KV (ACCORDING TO IEC-61000-4-2)

- NOTE (1): THE TEST SAMPLES HAVE RECOVERY TIME FOR 2 HOURS AT ROOM TEMPERATURE BEFORE THE FUNCTION CHECK. IN THE STANDARD CONDITIONS, THERE IS NO DISPLAY FUNCTION NG ISSUE OCCURRED.
- NOTE (2): THERE IS NO DISPLAY FUNCTION NG ISSUE OCCURRED, ALL THE COSMETIC SPECIFICATION IS JUDGED BEFORE THE RELIABILITY STRESS.
- NOTE (3): THE MODULE SHOULDN'T BE TESTED MORE THAN ONE CONDITION, AND ALL THE TEST CONDITIONS ARE INDEPENDENT.
- NOTE (4): WHEN THE LCD MODULE IS OPERATED AT A HIGHER AMBIENT TEMPERATURE THAN 60°C, THE PWM DUTY CYCLE OF THE LED BACKLIGHT SHOULD BE ADJUSTED TO BE LESS THAN (TBD)%. IF THE MODULE IS OPERATED AT A HIGHER DUTY CYCLE THAN (TBD)%, THEN THERE IS A POSSIBILITY OF DISTORTION AND IRREGULARITY OF THE PICTURE DUE TO LIQUID CRYSTAL BEHAVIOR.

NOTE (5): TESTING CONDITIONS AND INSPECTION CRITERIA

NO.	ITEM	TEST MODEL	INSPECTION CRITERIA
1	CURRENT CONSUMPTION		THE CURRENT CONSUMPTION SHOULD CONFORM TO THE PRODUCT SPECIFICATION.
2	CONTRAST	REFER TO SPECIFICATION	AFTER THE TESTS HAVE BEEN EXECUTED, THE CONTRAST MUST BE LARGER THAN HALF OF ITS INITIAL VALUE PRIOR TO THE TESTS.
3	APPEARANCE	VISUAL INSPECTION	DEFECT FREE

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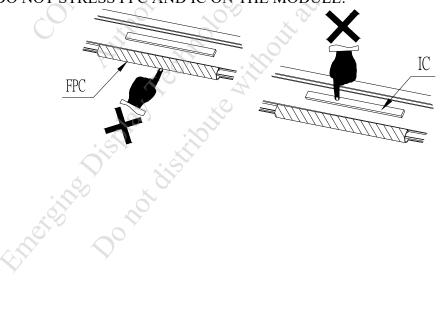
14. CAUTION

14.1 OPERATION

- 14.1.1 DO NOT CONNECT OR DISCONNECT MODULES TO OR FROM THE MAIN SYSTEM WHILE POWER IS BEING SUPPLIED .
- 14.1.2 USE THE MODULE WITHIN SPECIFIED TEMPERATURE; LOWER TEMPERATURE CAUSES THE RETARDATION OF BLINKING SPEED OF THE DISPLAY; HIGHER TEMPERATURE MAKES OVERALL DISPLAY DISCOLOR. WHEN THE TEMPERATURE RETURNS TO NORMALITY, THE DISPLAY WILL OPERATE NORMALLY.
- 14.1.3 ADJUST THE LC DRIVING VOLTAGE TO OBTAIN THE OPTIMUM CONTRAST.
- 14.1.4 POWER ON SEQUENCE INPUT SIGNALS SHOULD NOT BE SUPPLIED TO LCD MODULE BEFORE POWER SUPPLY VOLTAGE IS APPLIED AND REACHES THE SPECIFIED VALUE.

 IF ABOVE SEQUENCE IS NOT FOLLOWED, CMOS LSIS OF LCD MODULES MAY BE DAMAGED DUE TO LATCH UP PROBLEM.
- 14.1.5 NOT ALLOWED TO INFLICT ANY EXTERNAL STRESS AND TO CAUSE ANY MECHANICAL INTERFERENCE ON THE BENDING AREA OF FPC DURING THE TAIL BENDING BACKWARDS!

 DO NOT STRESS FPC AND IC ON THE MODULE!



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14.2 NOTICE

- 14.2.1 USE A GROUNDED SOLDERING IRON WHEN SOLDERING CONNECTOR I/O TERMINALS . FOR SOLDERING OR REPAIRING, TAKE PRECAUTION AGAINST THE TEMPERATURE OF THE SOLDERING IRON AND THE SOLDERING TIME TO PREVENT PEELING OFF THETHROUGH-HOLE-PAD .
- 14.2.2 DO NOT DISASSEMBLE . EDT SHALL NOT BE HELD RESPONSIBLE IF THE MODULE IS DISASSEMBLED AND UPON THE REASSEMBLY THE MODULE FAILED .
- 14.2.3 DO NOT CHARGE STATIC ELECTRICITY, AS THE CIRCUIT OF THIS MODULE CONTAINS CMOS LSIS. A WORKMAN'S BODY SHOULD ALWAYS BE STATIC-PROTECTED BY USE OF AN ESD STRAP. WORKING CLOTHES FOR SUCH PERSONNEL SHOULD BE OF STATIC-PROTECTED MATERIAL.
- 14.2.4 ALWAYS GROUND THE ELECTRICALLY-POWERED DRIVER BEFORE USING IT TO INSTALL THE LCD MODULE. WHILE CLEANING THE WORK STATION BY VACUUM CLEANER, DO NOT BRING THE SUCKING MOUTH NEAR THE MODULE; STATIC ELECTRICITY OF THE ELECTRICALLY-POWERED DRIVER OR THE VACUUM CLEANER MAY DESTROY THE MODULE.
- 14.2.5 DON'T GIVE EXTERNAL SHOCK.
- 14.2.6 DON'T APPLY EXCESSIVE FORCE ON THE SURFACE.
- 14.2.7 LIQUID IN LCD IS HAZARDOUS SUBSTANCE. MUST NOT LICK AND SWALLOW.WHEN THE LIQUID IS ATTACH TO YOUR, SKIN, CLOTH ETC.WASH IT OUT THOROUGHLY AND IMMEDIATELY.
- 14.2.8 DON'T OPERATE IT ABOVE THE ABSOLUTE MAXIMUM RATING.
- 14.2.9 STORAGE IN A CLEAN ENVIRONMENT, FREE FROM DUST, ACTIVE GAS AND SOLVENT.
- 14.2.10 STORE WITHOUT ANY PHYSICAL LOAD.
- 14.2.11 REWIRING: NO MORE THAN 3 TIMES.